

RGCL80TK60D

600V 40A Field Stop Trench IGBT

V _{CES}	600V
I _{C(100°C)}	21A
V _{CE(sat) (Typ.)}	1.4V@I _C =40A
P _D	57W

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Soft Switching
- Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 4) Pb free Lead Plating ; RoHS Compliant

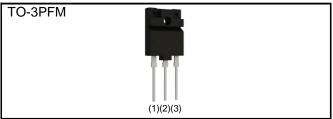
Applications

Partial Switching PFC

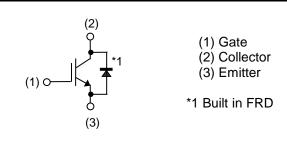
Discharge Circuit

Brake for Inverter

Outline



Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Tuno	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGCL80TK60D

●Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	600	V
Gate - Emitter Voltage		V _{GES}	±30	V
Collector Ourrent	$T_{\rm C} = 25^{\circ}{\rm C}$	Ι _C	35	А
Collector Current	T _C = 100°C	Ι _C	21	А
Pulsed Collector Current		I _{CP} ^{*1}	160	А
Diode Forward Current	$T_{\rm C} = 25^{\circ}{\rm C}$	I _F	26	А
Diode Forward Current	$T_{\rm C} = 100^{\circ}{\rm C}$	I _F	15	А
Diode Pulsed Forward Current		I _{FP} ^{*1}	100	А
Dower Dissignation	$T_{\rm C} = 25^{\circ}{\rm C}$	P _D	57	W
Power Dissipation	$T_{\rm C} = 100^{\circ}{\rm C}$	P _D	28	W
Operating Junction Temperature	•	Tj	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

*1 Pulse width limited by T_{jmax.}

Thermal Resistance

Parameter	Symbol	Values			Unit
	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance IGBT Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	2.62	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	3.93	°C/W

•IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector - Emitter Breakdown Voltage	BV _{CES}	I _C = 10μΑ, V _{GE} = 0V	600	-	-	V
Collector Cut - off Current	I _{CES}	V _{CE} = 600V, V _{GE} = 0V	-	-	10	μA
Gate - Emitter Leakage Current	I _{GES}	V_{GE} = ±30V, V_{CE} = 0V	-	-	±200	nA
Gate - Emitter Threshold Voltage	V _{GE(th)}	V _{CE} = 5V, I _C = 30.0mA	4.5	5.5	6.5	V
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_{C} = 40A, V_{GE} = 15V$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.4 1.6	1.8 -	V

•IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Symbol Conditions	Conditions		11-10		
Parameter		Min.	Тур.	Max.	Unit	
Input Capacitance	C _{ies}	V _{CE} = 30V	-	2340	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$	-	55	-	pF
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	43	-	
Total Gate Charge	Q_g	V _{CE} = 300V	-	98	-	
Gate - Emitter Charge	Q_{ge}	I _C = 40A	-	20	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	38	-	
Turn - on Delay Time	t _{d(on)}	$I_{\rm C} = 40$ A, $V_{\rm CC} = 400$ V	-	53	-	
Rise Time	t _r	$V_{GE} = 15V, R_G = 10\Omega$	-	34	-	
Turn - off Delay Time	$t_{d(off)}$	$T_j = 25^{\circ}C$	-	227	-	ns
Fall Time	t _f	Inductive Load	-	204	-	
Turn - on Switching Loss	E_{on}	*E _{on} includes diode	-	1.11	-	ml
Turn - off Switching Loss	E_{off}	reverse recovery	-	1.68	-	mJ
Turn - on Delay Time	t _{d(on)}	$I_{\rm C} = 40$ A, $V_{\rm CC} = 400$ V	-	48	-	
Rise Time	t _r	$V_{GE} = 15V, R_G = 10\Omega$	-	66	-	
Turn - off Delay Time	t _{d(off)}	T _j = 175°C	-	255	-	ns
Fall Time	t _f	Inductive Load	-	310	-	
Turn - on Switching Loss	E_{on}	*E _{on} includes diode	-	1.51	-	ml
Turn - off Switching Loss	E_{off}	reverse recovery	-	2.30	-	mJ
		$I_{\rm C} = 160$ A, $V_{\rm CC} = 480$ V				
Reverse Bias Safe Operating Area	RBSOA	$V_{P} = 600V, V_{GE} = 15V$	FU	LL SQUA	RE	-
		$R_{G} = 60\Omega, T_{j} = 175^{\circ}C$				

•FRD Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Parameter	Sumbol	Conditions	Values			Unit
Parameter	Symbol		Min.	Тур.	Max.	Unit
Diode Forward Voltage	V _F	I _F = 20A T _j = 25°C		1.45	1.9	V
	۷F	$T_j = 23 °C$ $T_j = 175°C$	-	1.45	-	v
Diode Reverse Recovery Time	t _{rr}		-	58	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	I _F = 20A V _{CC} = 400V	-	6.3	-	А
Diode Reverse Recovery Charge	Q _{rr}	di _F /dt = 200A/µs T _j = 25°C	-	0.20	-	μC
Diode Reverse Recovery Energy	Err		-	7.4	-	μJ
Diode Reverse Recovery Time	t _{rr}		-	256	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	$I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	10.4	-	А
Diode Reverse Recovery Charge	Q _{rr}		-	1.35	-	μC
Diode Reverse Recovery Energy	Err		-	146.5	-	μJ

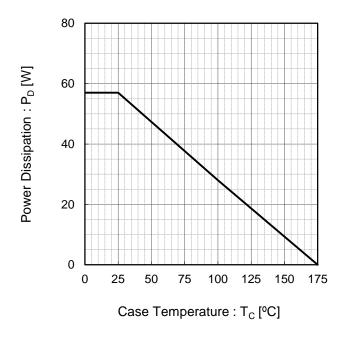


Fig.1 Power Dissipation vs. Case Temperature

Fig.2 Collector Current vs. Case Temperature

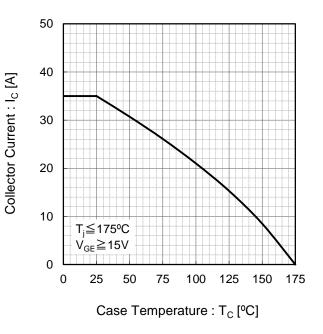
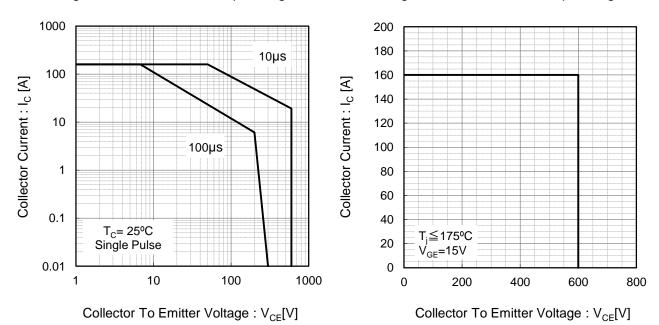


Fig.3 Forward Bias Safe Operating Area

Fig.4 Reverse Bias Safe Operating Area



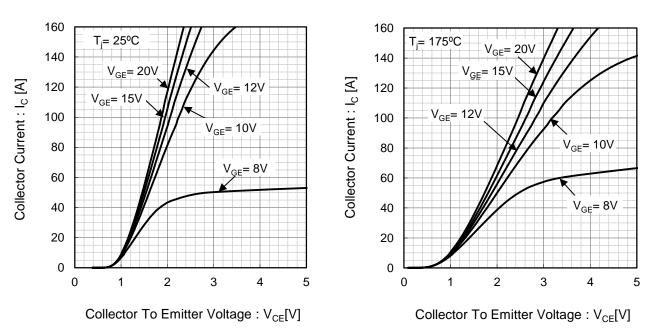
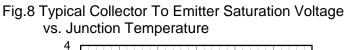
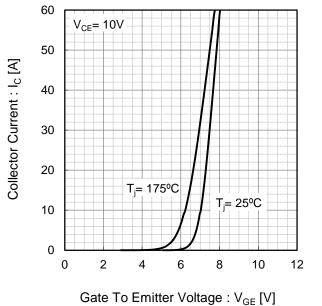


Fig.5 Typical Output Characteristics

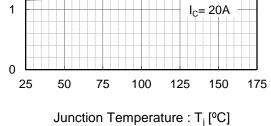
Fig.6 Typical Output Characteristics

Fig.7 Typical Transfer Characteristics





V_{GE}= 15V Collector To Emitter Saturation Voltage 3 I_C= 80A : V_{CE(sat)} [V] 2 $I_{C} = 40A$



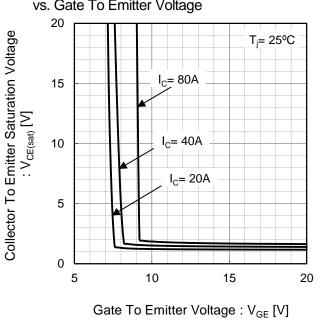


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

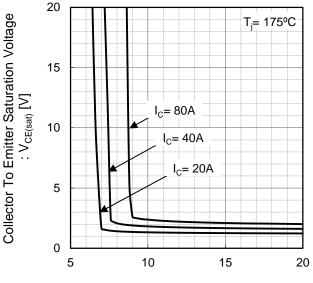
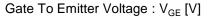


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



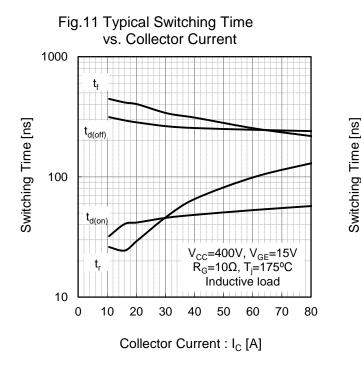
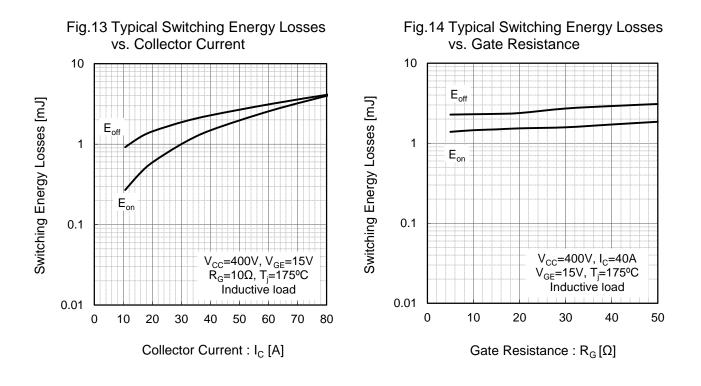


Fig.12 Typical Switching Time vs. Gate Resistance 1000 t_{d(off)} 100 t, t_{d(on)} V_{CC}=400V, I_C=40A V_{GE}=15V, T_j=175°C Inductive load 10 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$



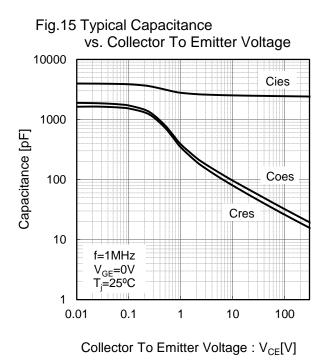
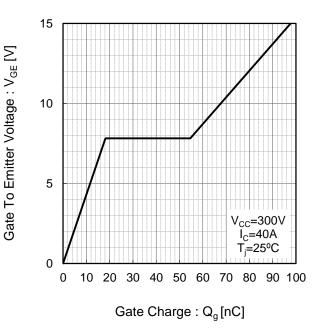


Fig.16 Typical Gate Charge



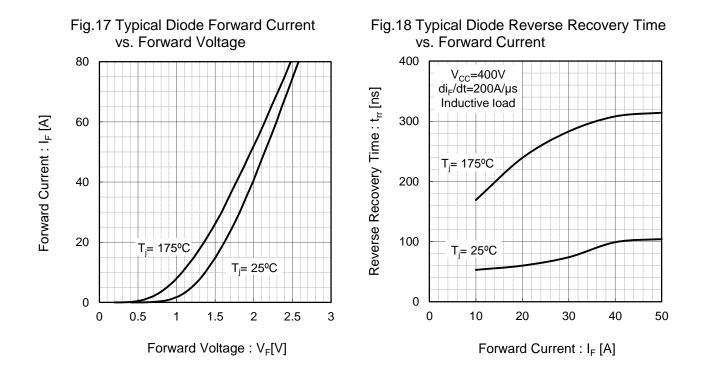


Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

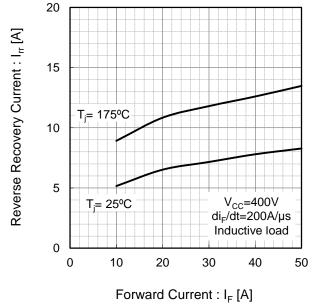
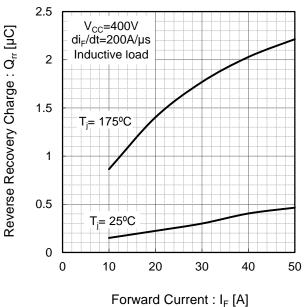


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



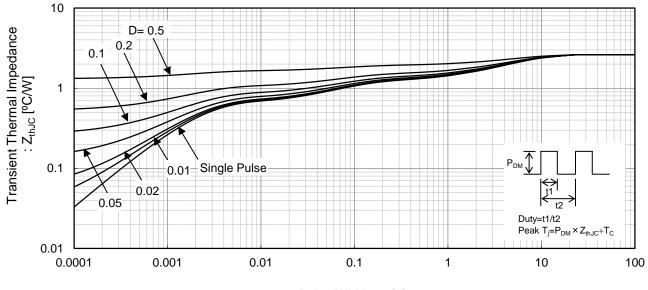
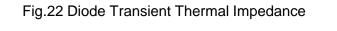
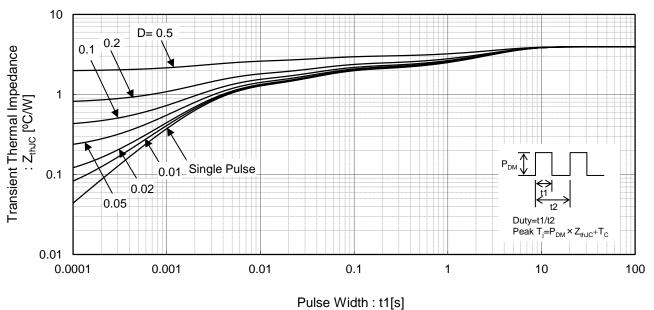


Fig.21 IGBT Transient Thermal Impedance

Pulse Width : t1[s]





●Inductive Load Switching Circuit and Waveform

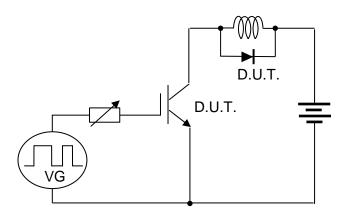


Fig.23 Inductive Load Circuit

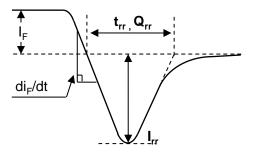
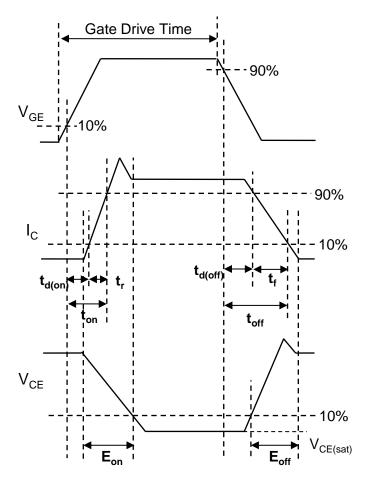


Fig.25 Diode Reverce Recovery Waveform





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